



**POLITECNICO**  
MILANO 1863

# Low-noise InGaAs/InP SPAD with photon detection efficiency exceeding 50% at 1550 nm

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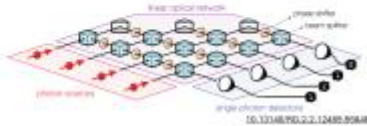
# OUTLINE

## Quantum information and communication

### Quantum cryptography (QKD)

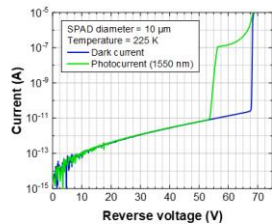
#### Requirements:

- High detection efficiency at 1550 nm
- Low noise
- High count rate



- Design of front-illuminated planar InGaAs/InP SPAD

## Current-voltage curves



Breakdown voltage: **67.5 V**  
Punch-through voltage: **53 V**

Dark current is mainly due to surface generation → not relevant for SPAD

- Experimental characterization

## State-of-the-art comparison

Ref.	Temperature (K)	PDE (%)	DCR (cps)	Afterpulsing probability
<b>This work</b>	225	17.3 - 51	1.9 k - 18 k	4.5% - 8.1% with long $T_{\text{off}}$ and HO = 1 $\mu\text{s}$
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He et al.	247	8 - 55.4	1000 - 43.8k	N.A.
Zhang et al.	233	30 - 40	127 - 1000	3% - 22% with $T_{\text{off}} = 1$ ns and HO = 20 ns

- Conclusions



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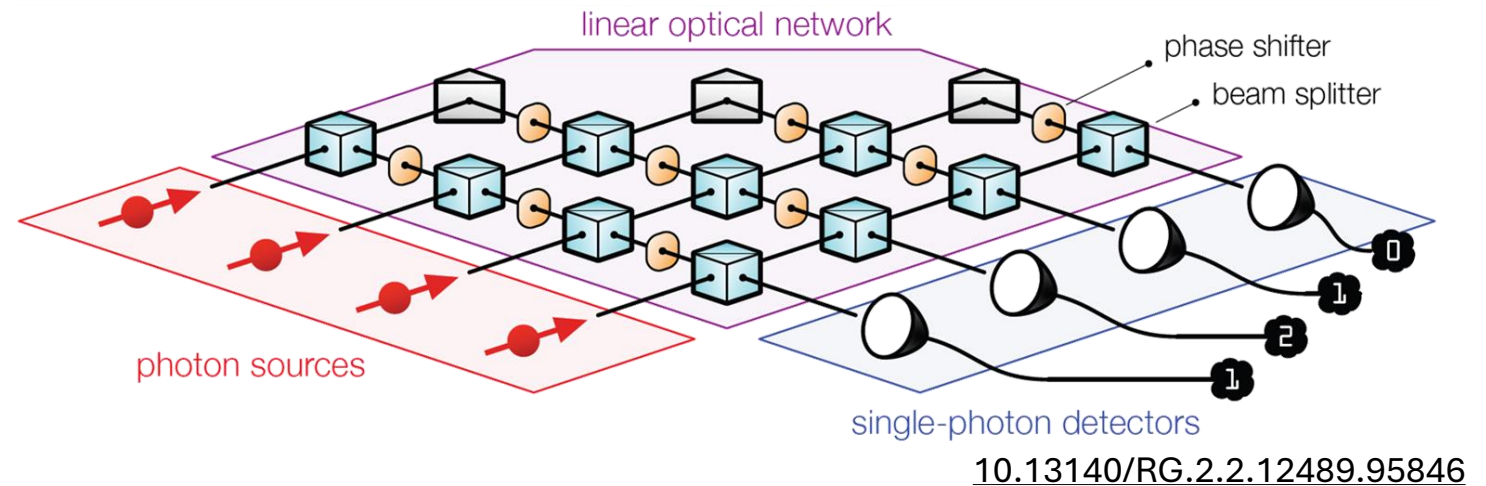
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# Quantum information and communication

## Quantum cryptography (QKD)

Requirements:

- *High detection efficiency at 1550 nm*
- *Low noise*
- *High count rate*



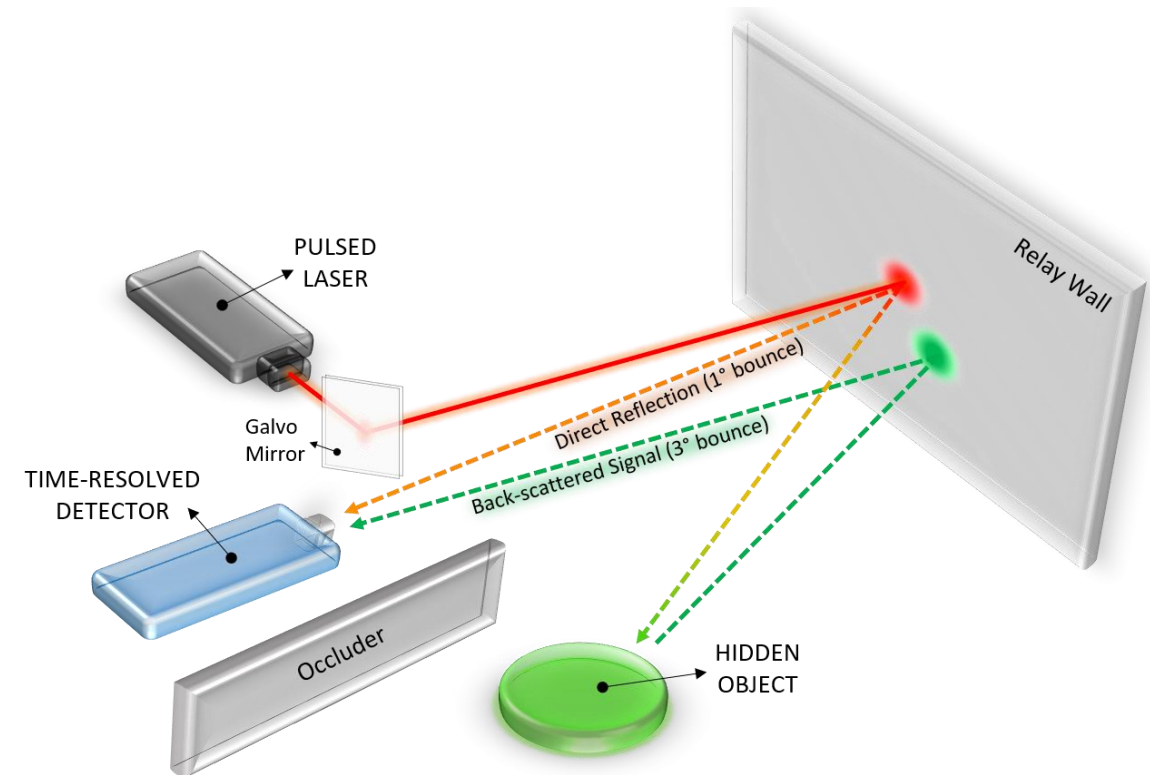
# Imaging applications

Light detection and ranging (LiDAR)

Non-line-of-sight (NLOS) imaging

Requirements:

- High efficiency in SWIR range for eye-safety
- Sharp timing response



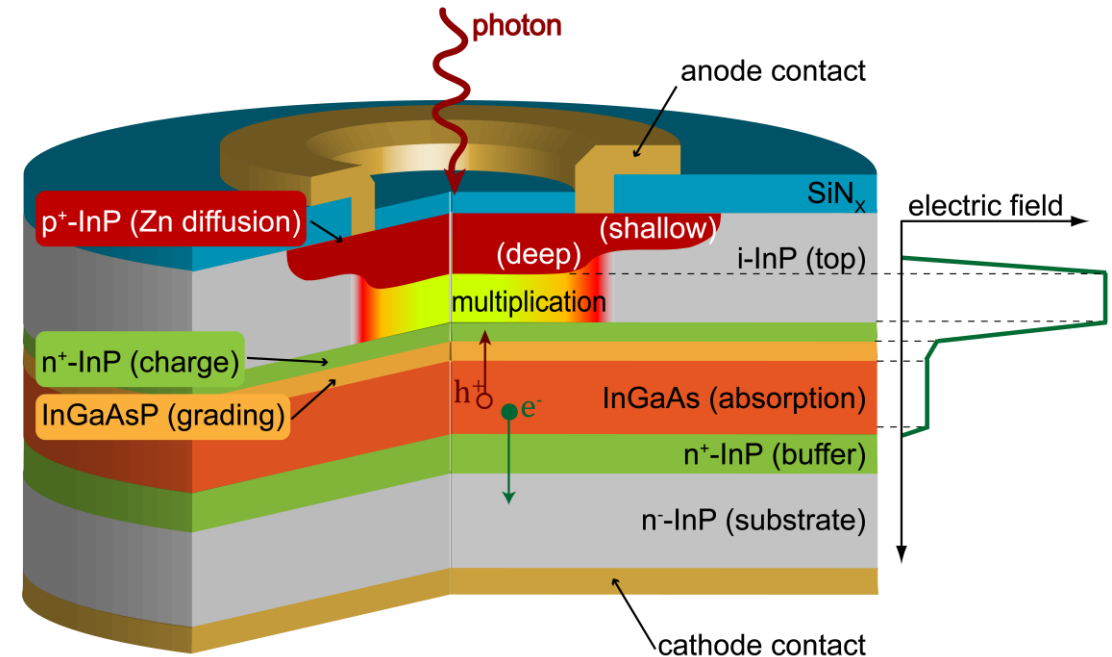
# Front-illuminated planar InGaAs/InP SPAD

$\text{In}_{0.53}\text{Ga}_{0.47}\text{As}$  ( $E_G = 0.75$  eV):

- Absorption up to  $\lambda = 1700$  nm
- Unsuitable for avalanche multiplication (tunneling)

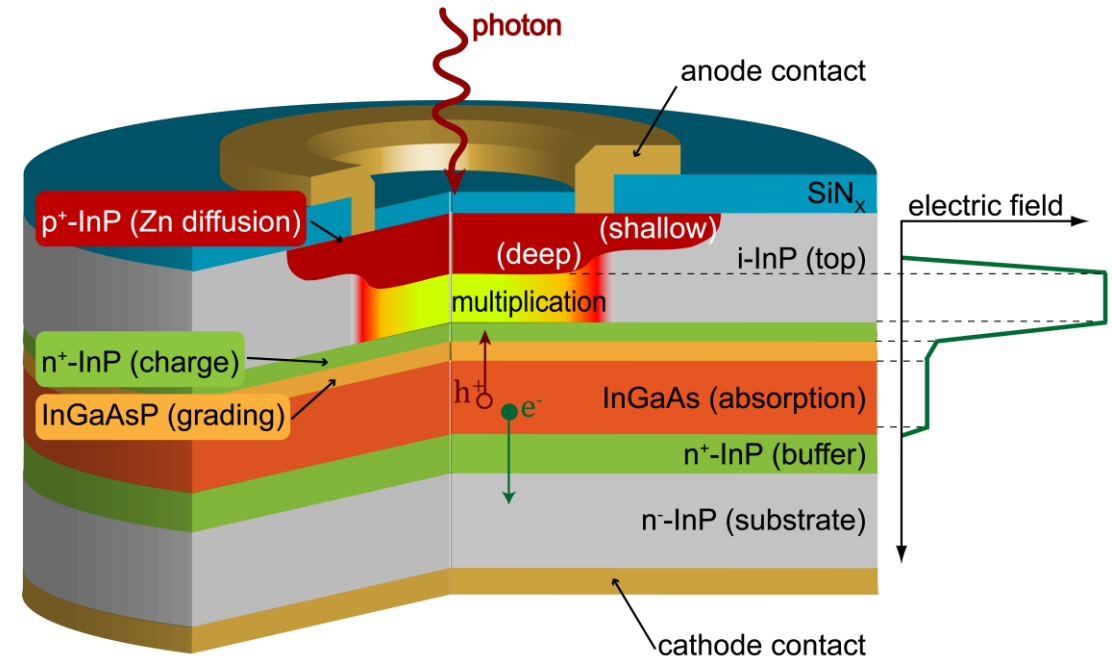
$\text{InP}$  ( $E_G = 1.35$  eV) – *lattice matched*

→ **Separate Absorption Charge and Multiplication (SACM)**



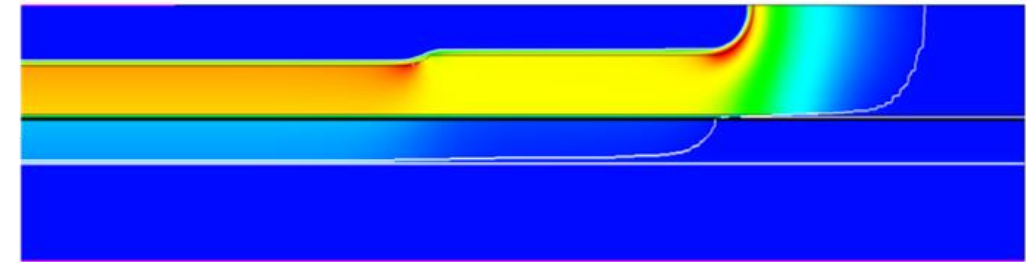
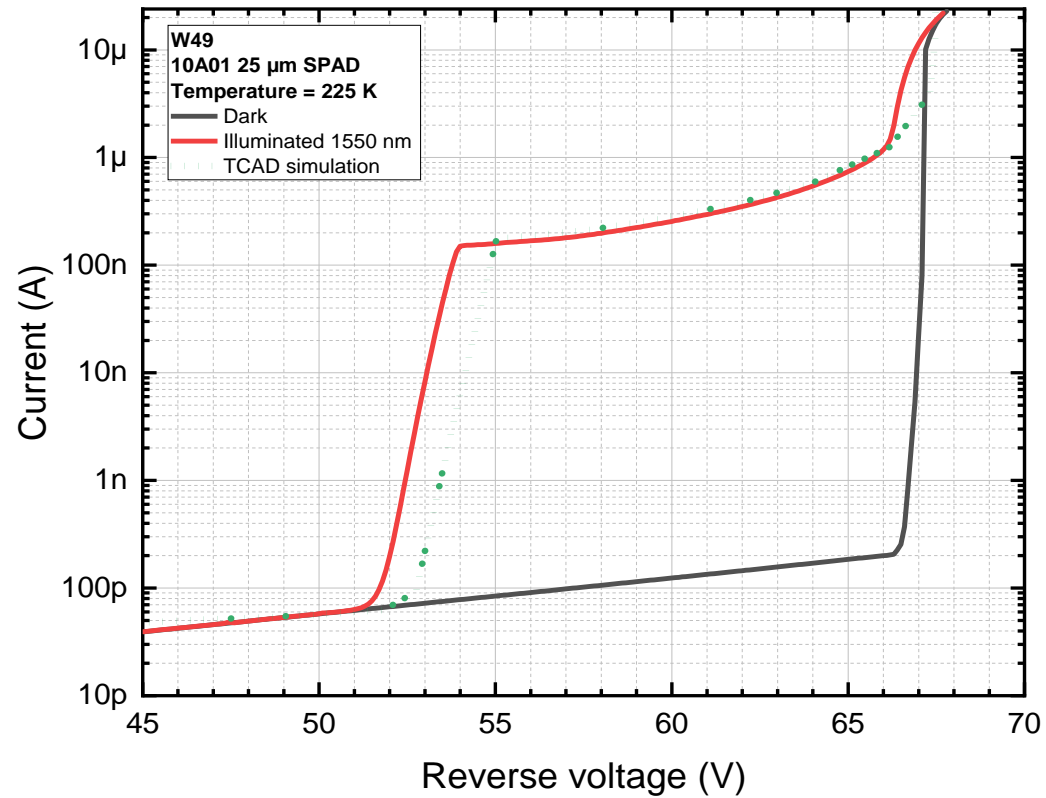
# Front-illuminated planar InGaAs/InP SPAD

- **Charge layer** (n-doped)  
→ Shapes the electric field
- **Double zinc diffusion** (p-dopant)  
→ Defines active area
- **5 grading layers** (InGaAsP)  
→ Reduces barrier for facilitating photo-generated holes transit

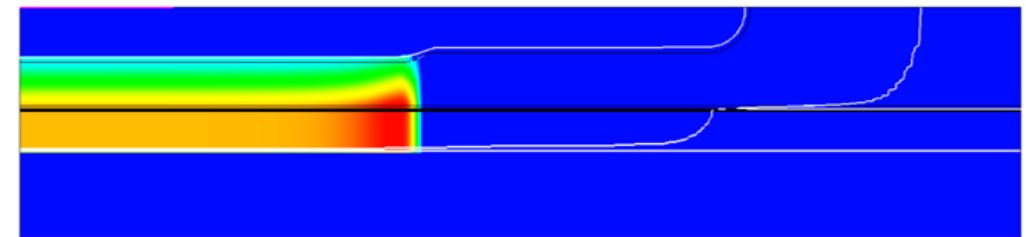


# TCAD modeling and simulation

TCAD simulations (*Sentaurus, Matlab*) → optimize the internal structure for different objectives



Electric field (V/cm)



Avalanche triggering probability (%)

# Avalanche triggering probability: diffusion of carriers

**Avalanche triggering probability**  
(Oldham *et al.*):

$$\frac{dP_e}{dx} = (1 - P_e) \cdot \alpha \cdot (P_e + P_h - P_e \cdot P_h)$$

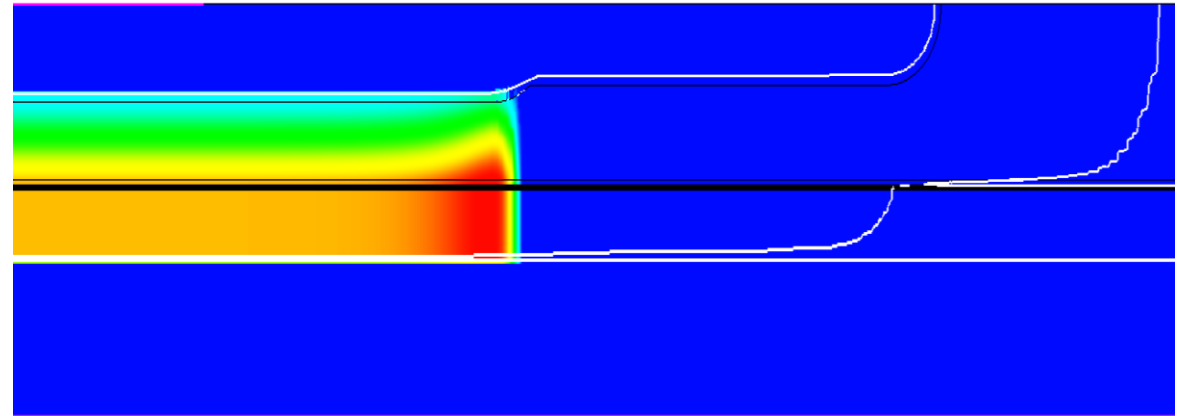
$$\frac{dP_h}{dx} = -(1 - P_h) \cdot \beta \cdot (P_e + P_h - P_e \cdot P_h)$$

Carrier **diffusion** from quasi-neutral regions:

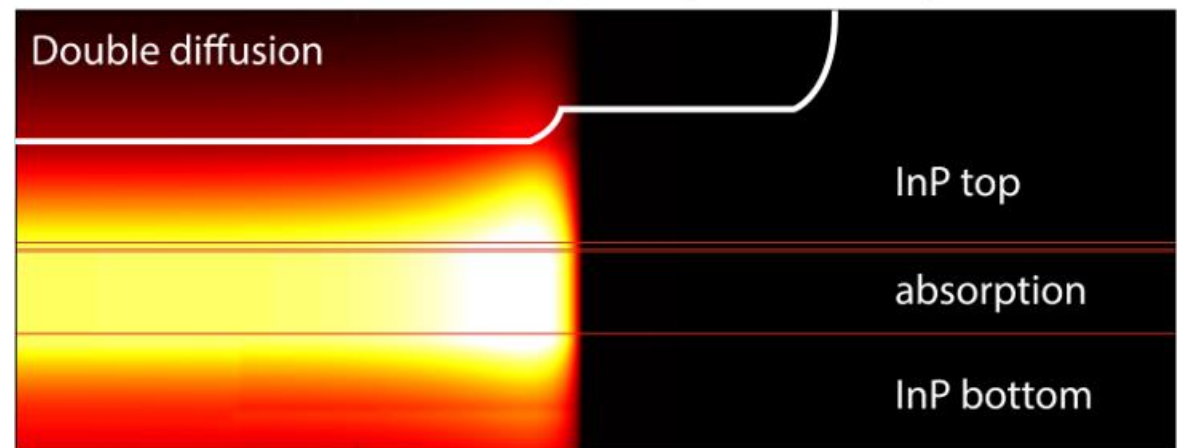
$$P_e(y) = P_e(w_p) e^{\frac{y-w_p}{L_e}}, \text{ for } y < w_p$$

$$P_h(y) = P_h(w_n) e^{\frac{w_n-y}{L_h}}, \text{ for } y > w_n$$

**Avalanche triggering probability**

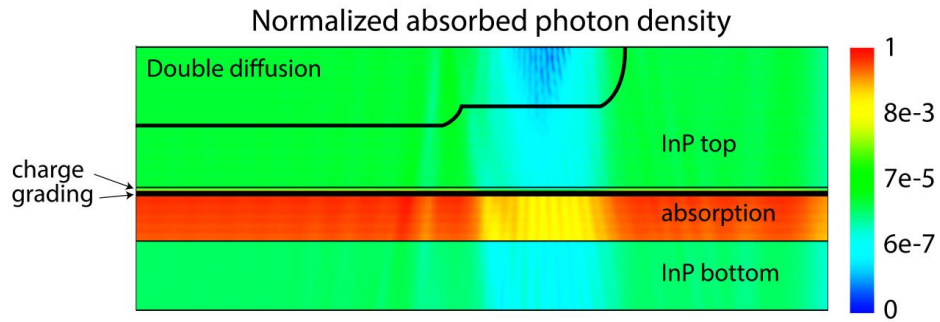


**Extended avalanche triggering probability**





# Optical simulations: InP and InGaAs complex refractive index



$$n^* = n + ik$$

$n$  = accounts for refraction

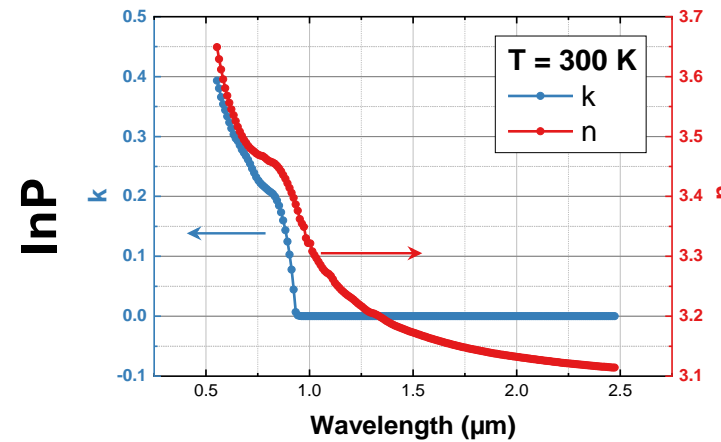
$k$  = accounts for absorption

→ Absorption coefficient:

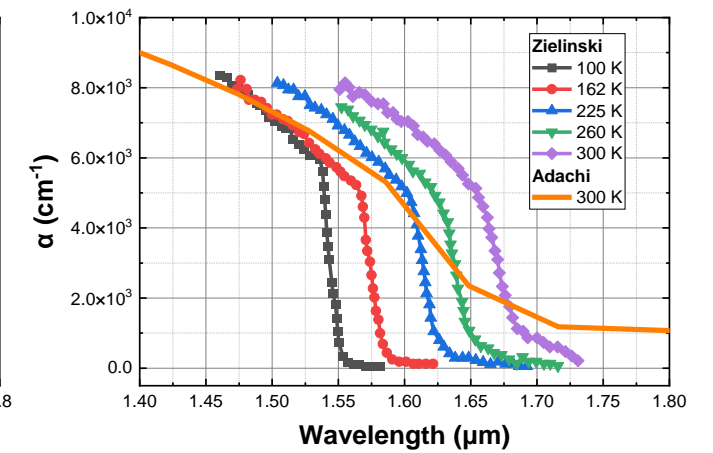
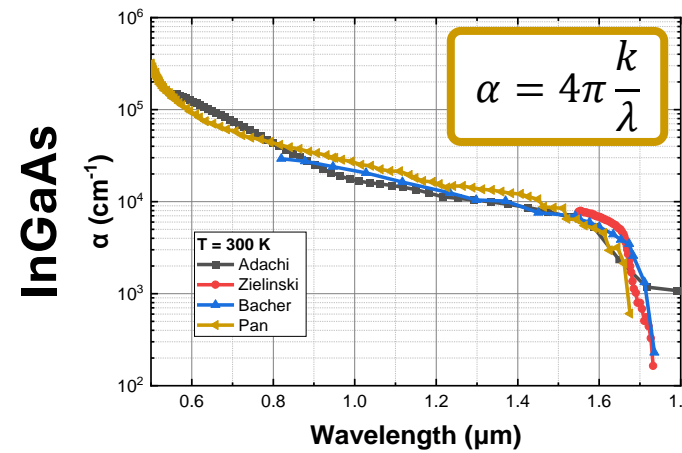
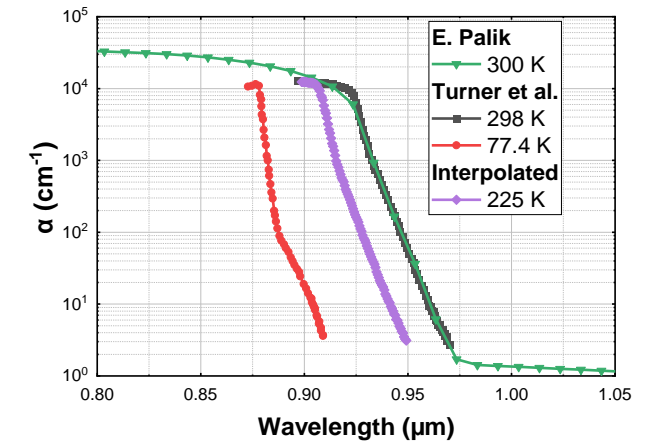
$$\alpha = 4\pi \frac{k}{\lambda}$$

Temperature dependence extrapolated from range around the cut-off wavelength

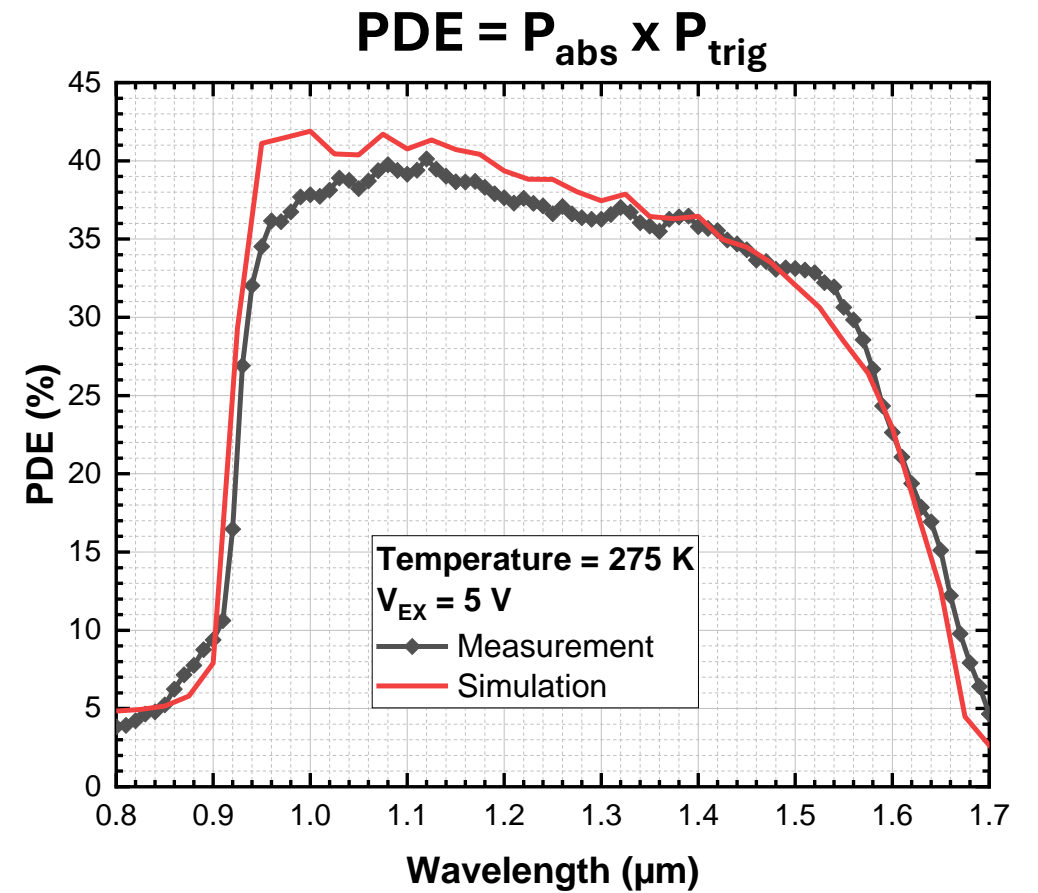
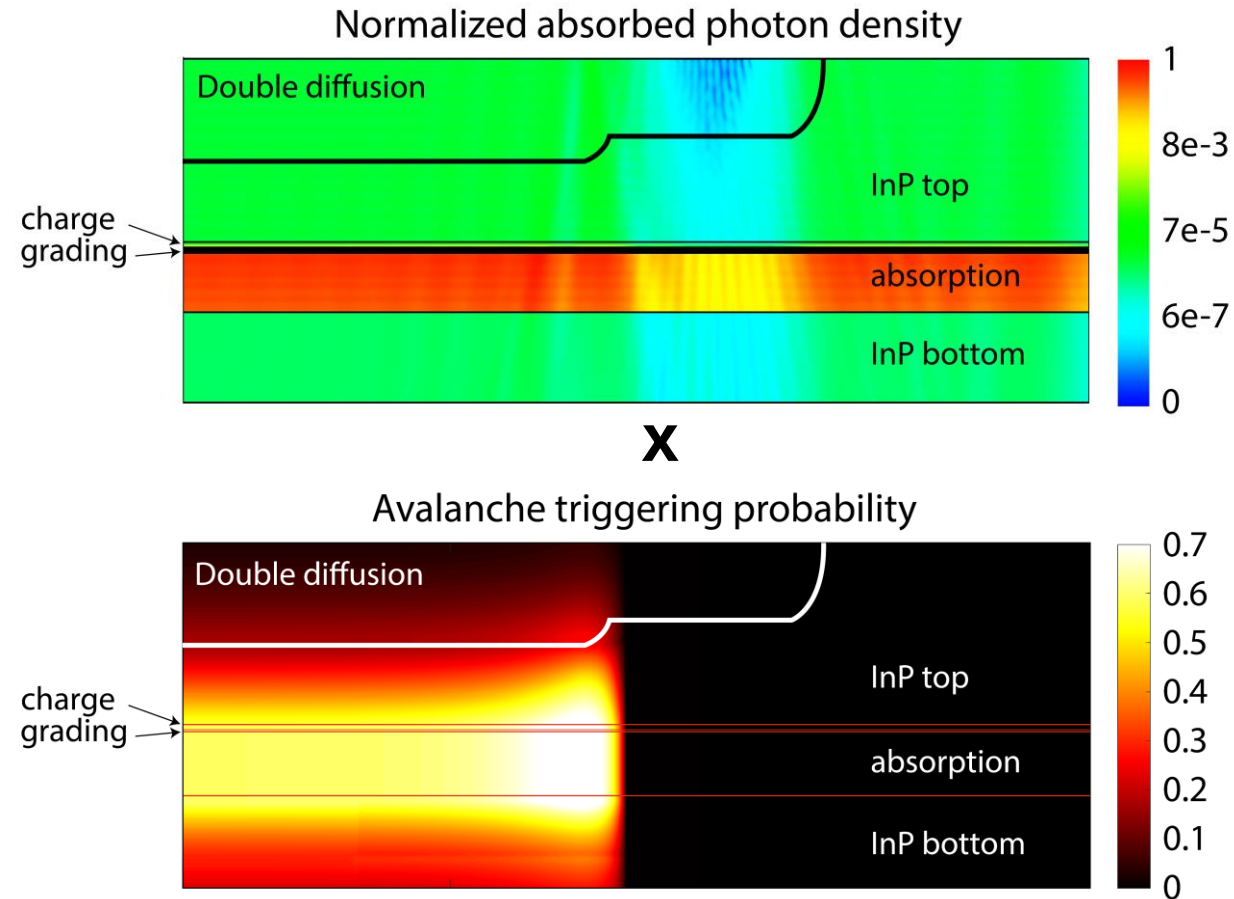
Absorption coefficient ( $\alpha$ ) at RT



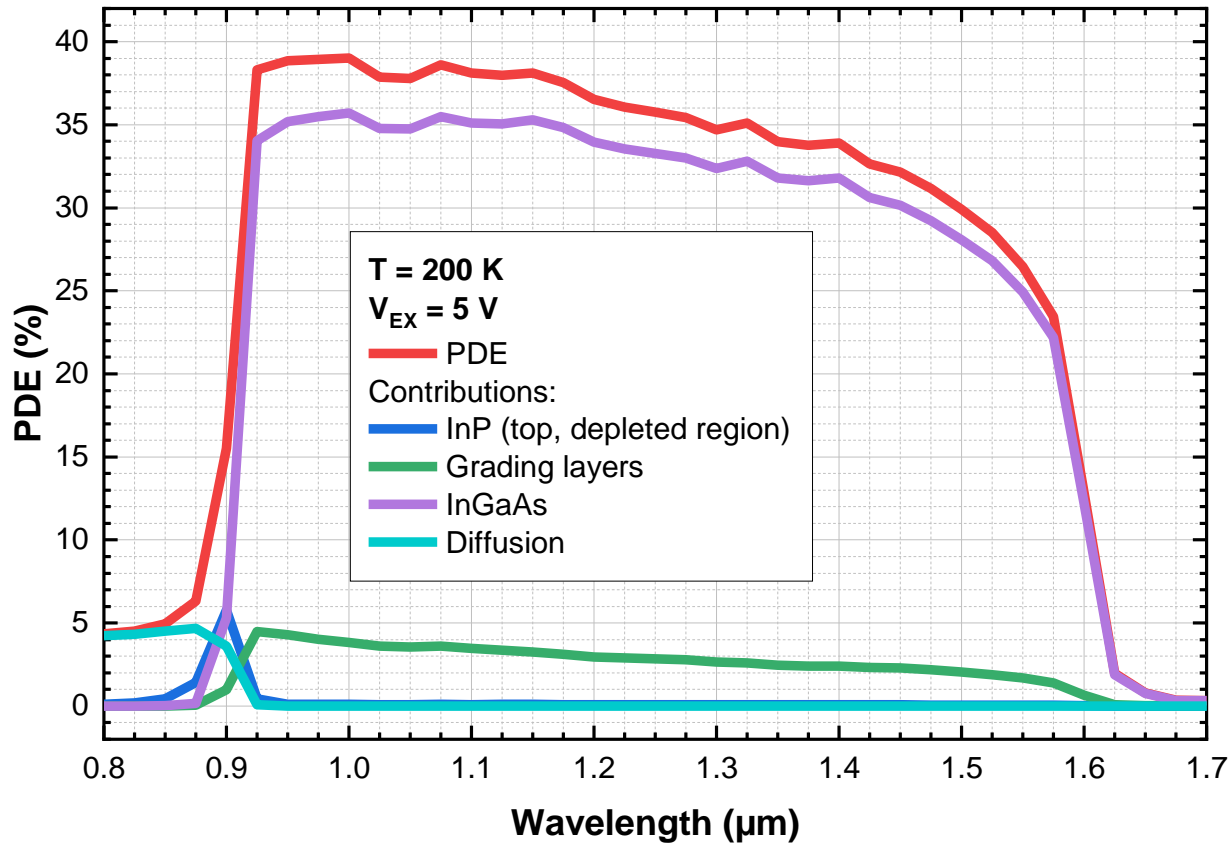
Temperature dependence of  $\alpha$



# Photon detection efficiency simulation



# PDE simulation results

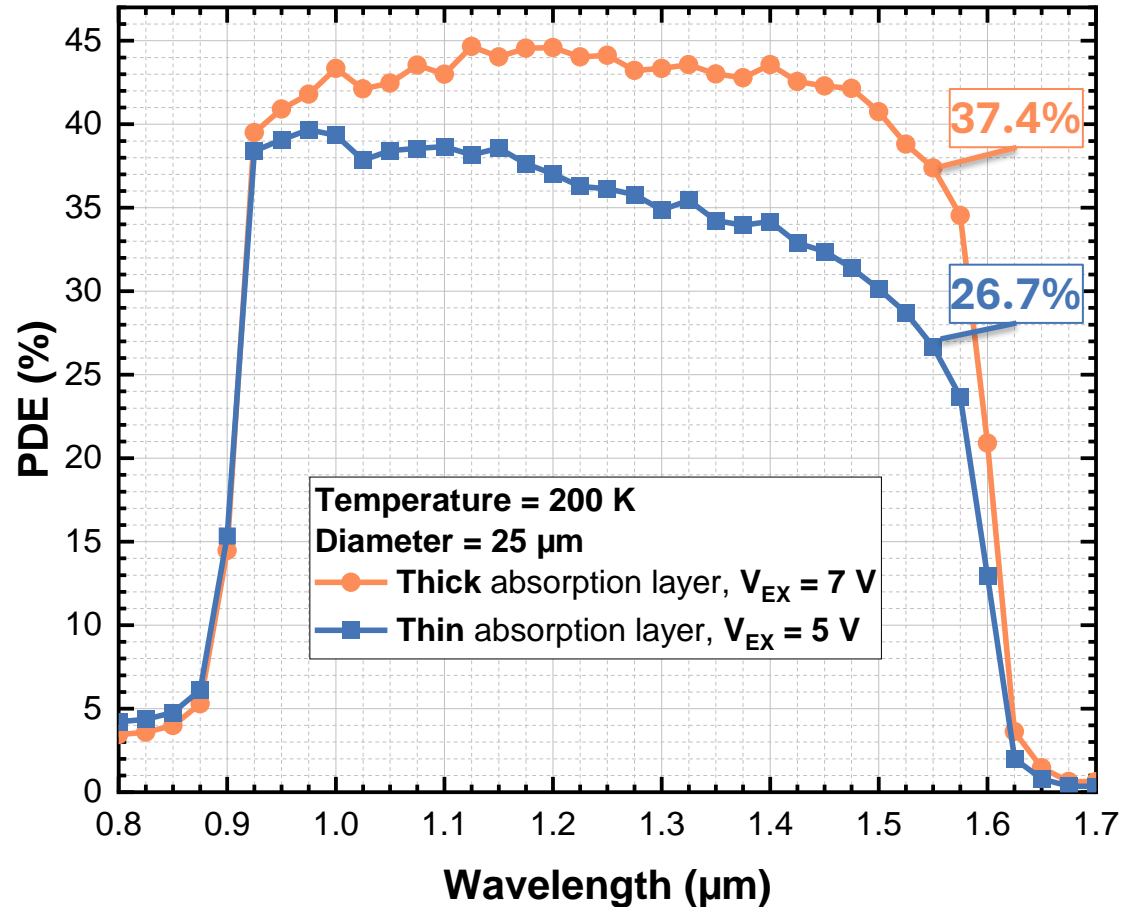


*Contributions* to PDE from various regions:

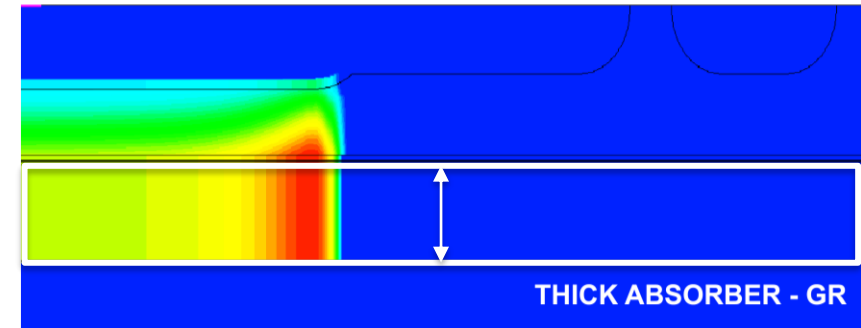
- **InGaAs** is the **main contribution**
- Carrier diffusion is only relevant up to 900 nm
- InGaAsP grading layers have a non-negligible contribution (about 10% of the total PDE)
- InP bottom layers do not contribute to PDE

# Enhanced PDE InGaAs/InP SPAD: TCAD modeling

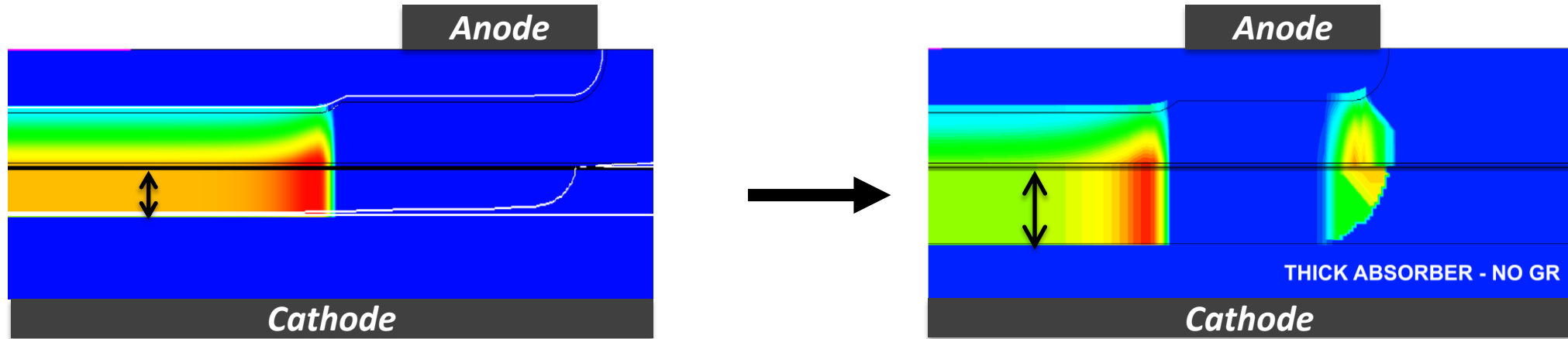
PDE estimated from TCAD simulations



**Thicker InGaAs absorption layer**  
&  
Optimized double zinc diffusion profile,  
Charge layer thickness

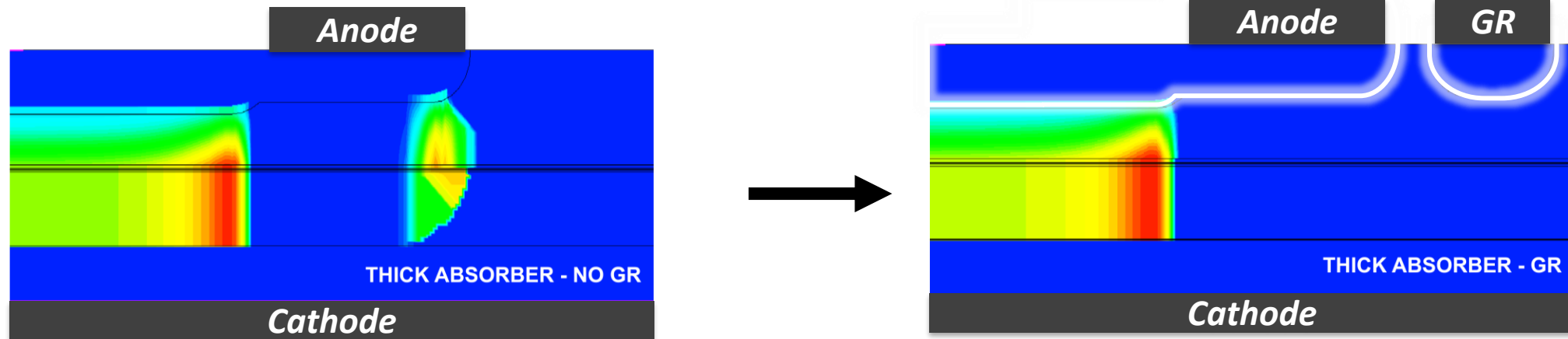


# Structure for high photon detection efficiency



**Thicker InGaAs absorption layer** → Higher noise, reduced active area uniformity

# Structure for high photon detection efficiency



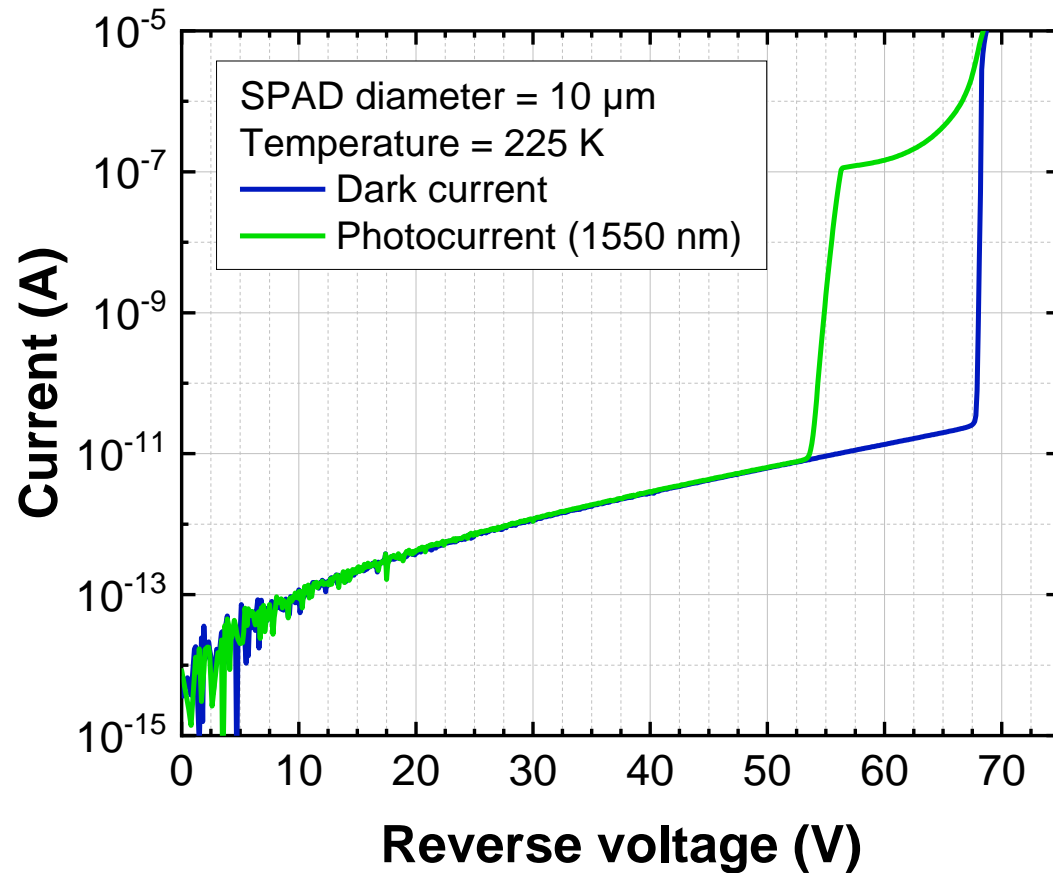
**TCAD simulations** with commercial software and custom models:

- Optimized double diffusion → Enhanced active-area uniformity
- Contacted **guard ring** → Prevent edge breakdown, mitigate charge persistence

Small active area (10  $\mu\text{m}$  diameter):

→ Reduced noise, still good for fiber pigtailling

# Current-voltage curves

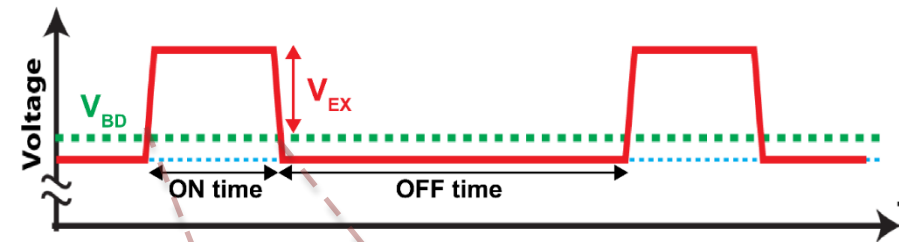
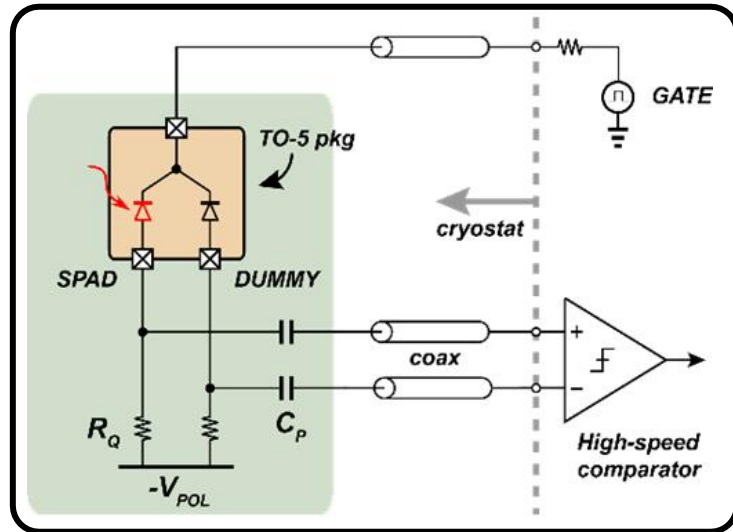


Breakdown voltage: **67.5 V**

Punch-through voltage: **53 V**

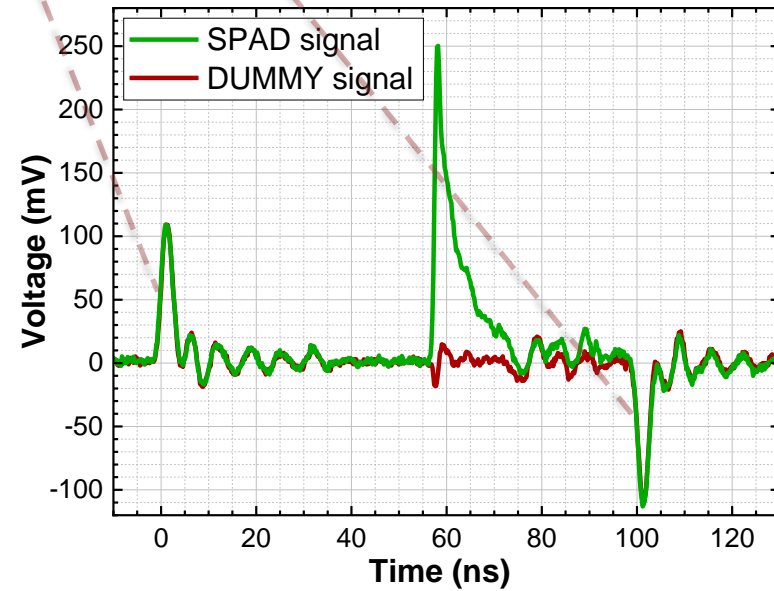
Dark current is mainly due to surface generation  $\rightarrow$  not relevant for SPAD

# Gated-mode SPAD operation



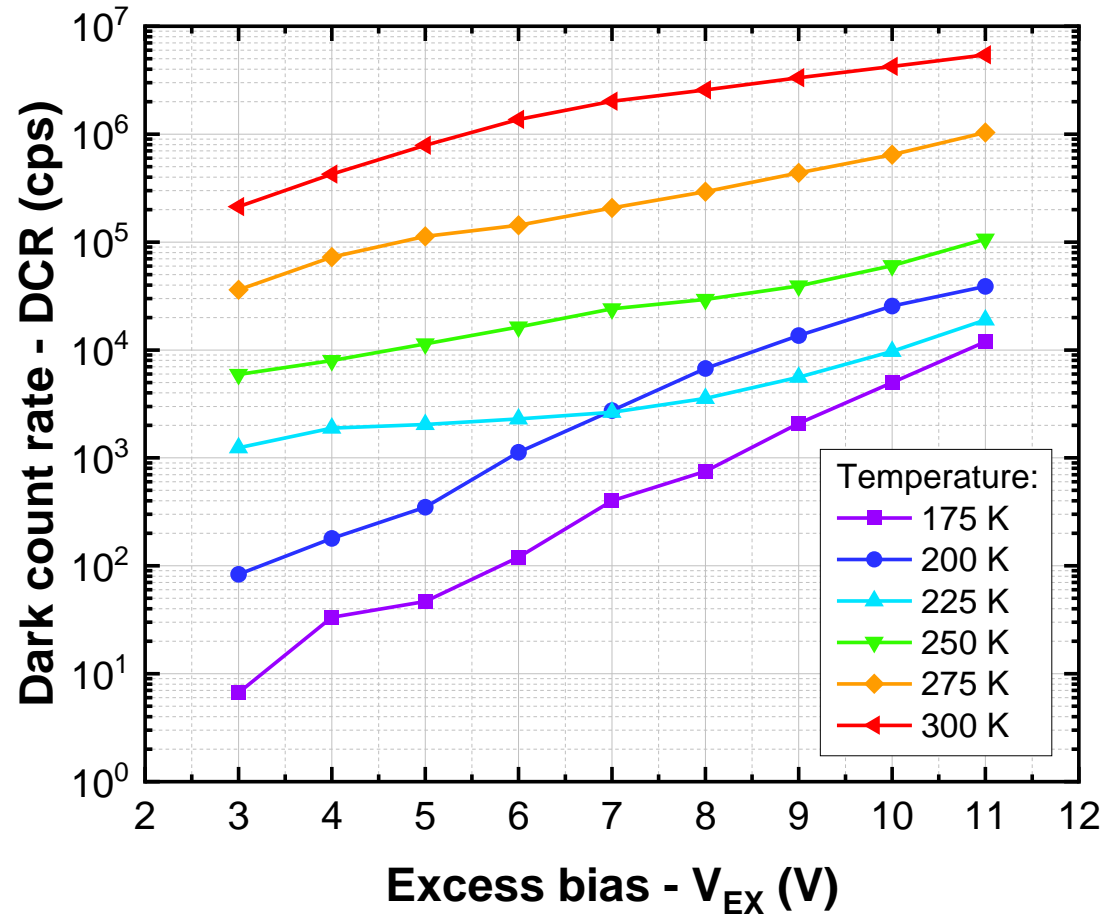
## Basic schematic for *square-wave gating*

- Passive quenching in the starting phase
- Complete quenching by pulling down the gate voltage
- Long enough OFF time to limit afterpulsing
- **SPAD-DUMMY** approach to subtract feed-through





# Dark count rate

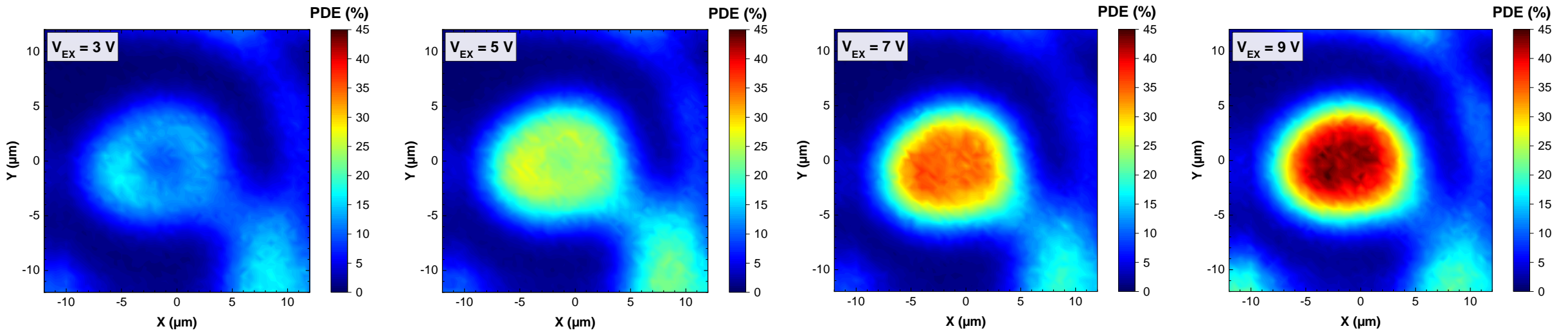
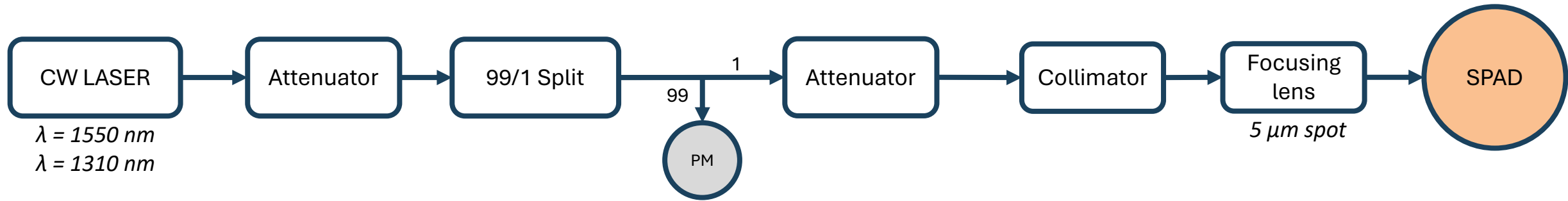


Long  $T_{OFF}$  (100  $\mu$ s) to avoid afterpulsing

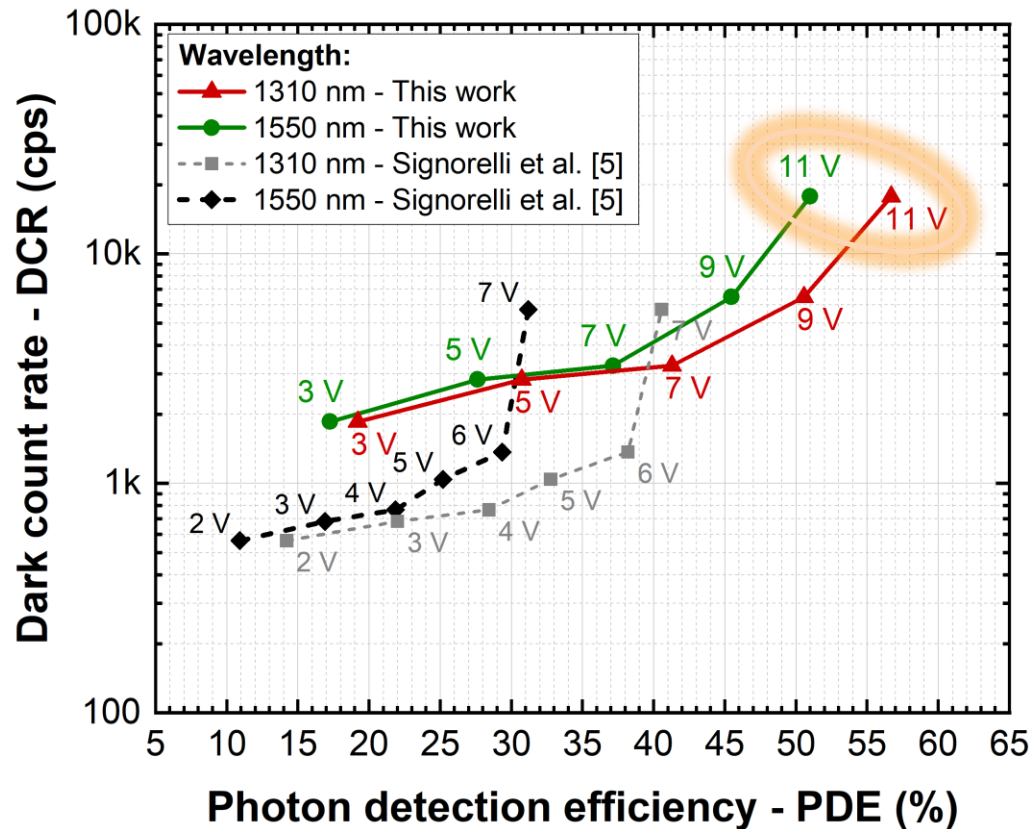
At  $T = 225$  K:  
DCR of few kcps

At  $T \leq 200$  K:  
Charge persistence is stronger

# Photon detection efficiency



# Photon detection efficiency



Laser source:

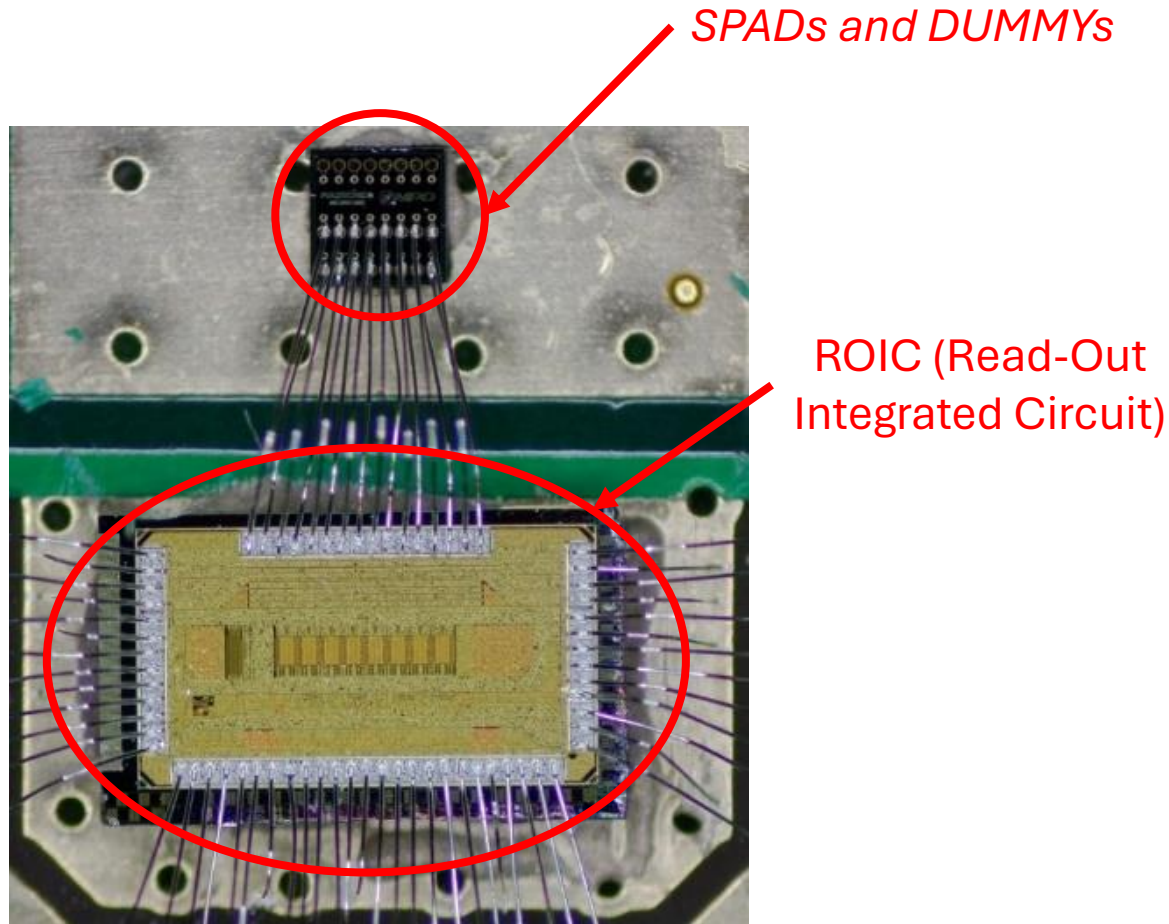
- $\lambda = 1550$  nm or  $\lambda = 1310$  nm
- $5 \mu\text{m}$  laser spot size

Photon detection efficiency:

- up to **51%** for  $\lambda = 1550$  nm
- up to **57%** for  $\lambda = 1310$  nm

with DCR = 18 kcps

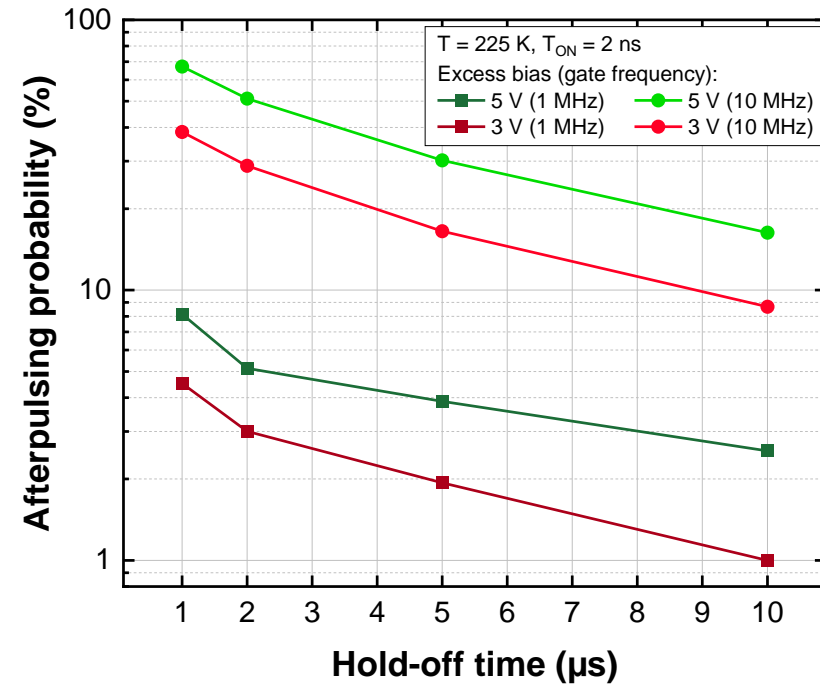
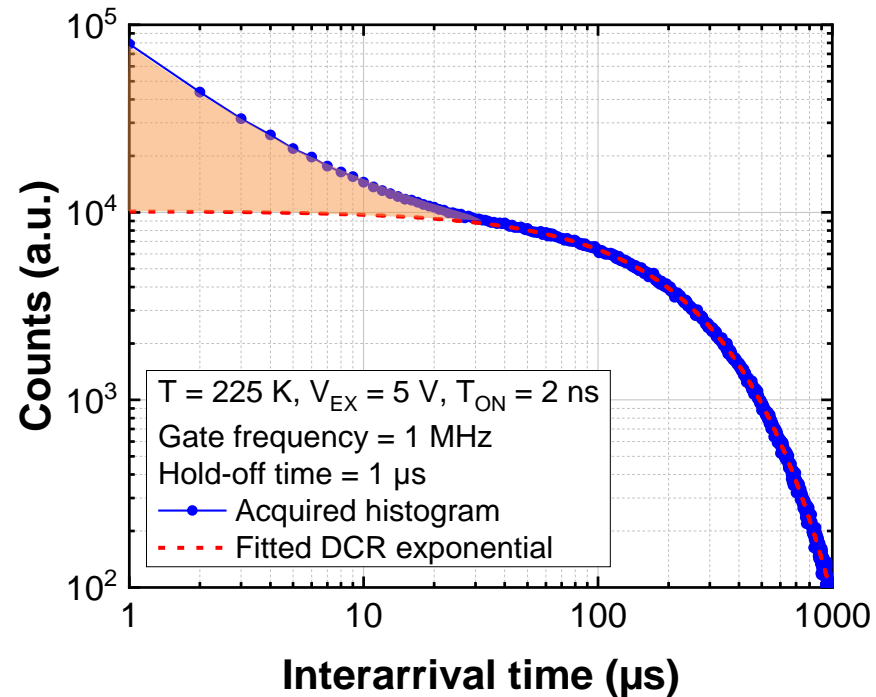
# Afterpulsing probability



Read-out integrated circuit (**ROIC**):

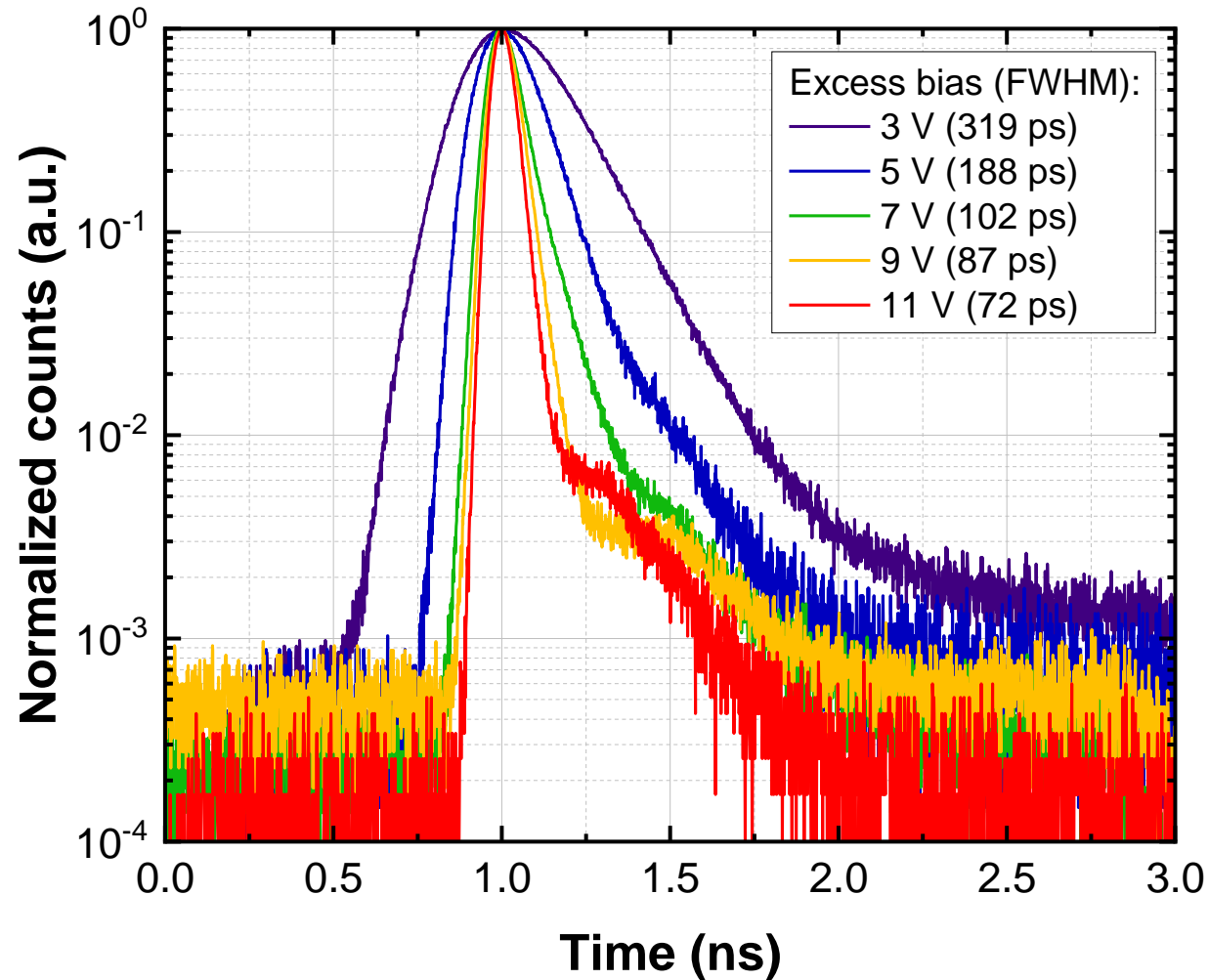
- 0.16  $\mu\text{m}$  BCD technology
- Up to 8 SPADs (and DUMMYS)
- Up to 5 V excess bias
- Up to 100 MHz gate
- Tunable hold-off time
- ~ **1-2 ns** quenching time

# Afterpulsing probability



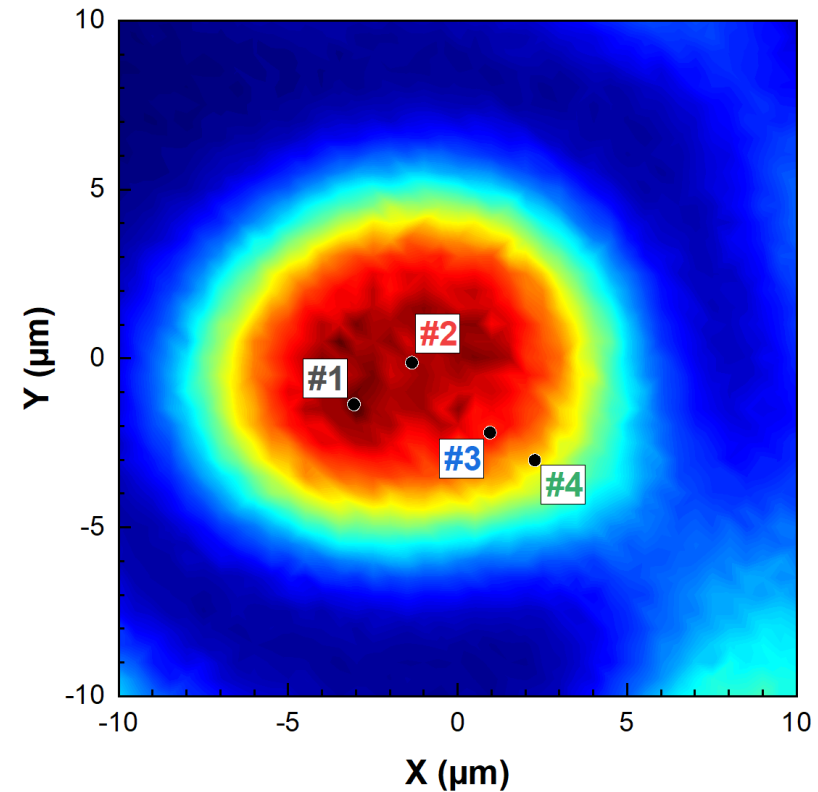
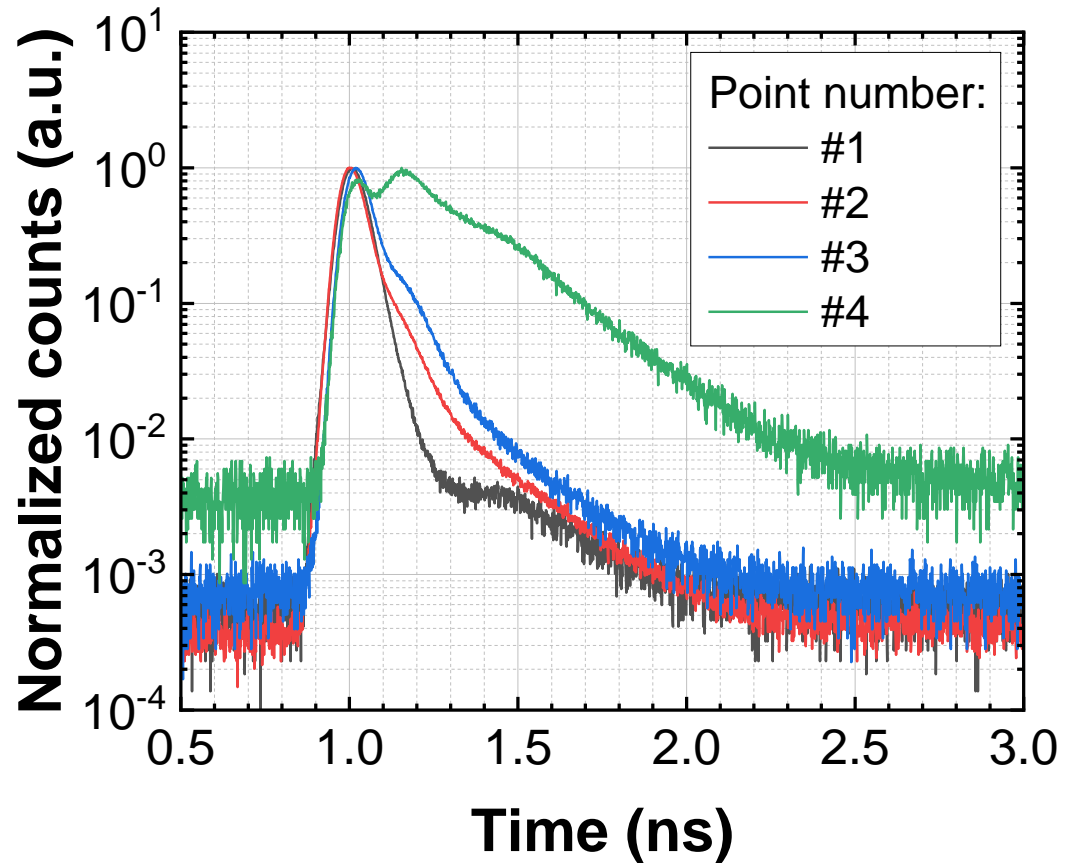
High gate frequency, hold-off time enforced after every avalanche.  
**Afterpulsing is just few percent at 225 K and 1 MHz gate frequency.**

# Temporal response



- **18 ps** (FWHM) pulsed laser
- **$\lambda = 1550$  nm,  $T = 225$  K**
- Laser spot **focused** on a high-efficiency peak inside the active area

# Temporal response



Position and amplitude of secondary peak depend on the laser position  
→ Residual non-uniformities inside the active area

# State-of-the-art comparison

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# CONCLUSIONS

- **Optimized InGaAs/InP SPAD structure for enhanced PDE**
  - TCAD simulations to tailor double diffusion depth, charge layer and absorption layer thicknesses
  - PDE simulations to estimate the PDE enhancement
- **Best-in-class PDE (up to 51%) at 1550 nm with:**
  - DCR < 20 kcps
  - Timing jitter ~ 70 ps (FWHM)
- **Reduced afterpulsing** (few percent) thanks to a custom-designed integrated circuit



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# Thank you!



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